

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **CHNG HAN SHEN, MATTHEW LIM ENG HAN**

For: **VARIOUS STRUCTURE/HEIGHT BUMPS FOR WAFER LEVEL-CHIP SCALE PACKAGE**

Enclosed are:

- ☒ 7 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Advanpack Solutions Pte, Ltd.**
- ☐ An associate power of attorney ☒ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 385.
TOTAL CLAIMS	35 -20=	15	x 9 =	\$ 135.
INDEP CLAIMS	3 -3=	0	x 43 =	\$ 0.
SUB TOTAL				\$ 520.
ASSIGNMENT				\$40.
TOTAL				\$ 560.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of **\$ 560.** A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR §1.16.
- ☒ Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761

EXPRESS MAIL CERTIFICATE

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Washington, DC 20231. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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